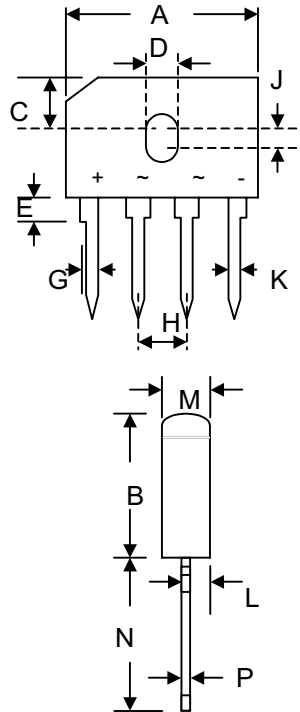


Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards
- UL Recognized File # E223064
- Green Products in Compliance with the RoHS Directive

Mechanical Data

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 4.0 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



Dim	GBU			
	Min	Max	Min	Max
A	21.8	22.3	0.858	0.878
B	18.30	18.80	0.720	0.740
C	7.40	7.90	0.291	0.311
D	3.50	4.10	0.138	0.161
E	1.52	2.03	0.060	0.080
G	2.16	2.54	0.085	0.1
H	4.83	5.33	0.190	0.210
J	1.65	2.16	0.065	0.085
K	1.65	2.03	0.065	0.080
L	0.76	1.02	0.030	0.040
M	3.30	3.56	0.130	0.140
N	17.50	18.00	0.689	0.709
P	0.46	0.56	0.018	0.022
	In mm		In inch	

Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	GBU4A-G	GBU4B-G	GBU4D-G	GBU4G-G	GBU4J-G	GBU4K-G	Unit
Peak Repetitive Reverse Voltage	V _{RRM}							V
Working Peak Reverse Voltage	V _{RWM}	50	100	200	400	600	800	
DC Blocking Voltage	V _R							
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	V
Average Rectified Output Current	I _O	@T _C = 100°C: 4.0 @T _A = 40°C: 3.0						A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	150						A
I ² t Rating for Fusing (t < 8.35ms)	I ² t	93						A ² s
Forward Voltage (per element)	V _{FM}	1.0						V
Peak Reverse Current	I _R	@T _A = 25°C: 5.0 @T _C = 100°C: 500						μA
Typical Thermal Resistance (per leg) (Note 1)	R _{θJA}	19						K/W
Typical Thermal Resistance (per leg) (Note 2)	R _{θJC}	4.0						K/W
Operating and Storage Temperature Range	T _j , T _{STG}	-55 to +150						°C

Note: 1. Thermal resistance junction to ambient, mounted on PCB at 9.5mm lead length with 12mm² copper pads.
2. Thermal resistance junction to case, mounted on 5.0 x 4.0 x 0.8cm thick AL plate.

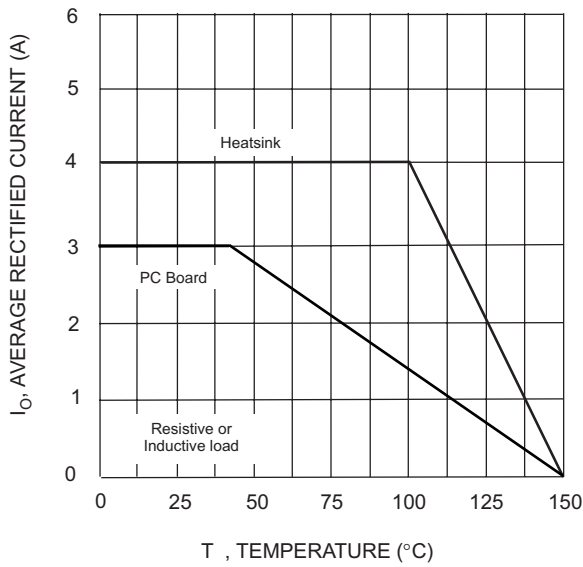


Fig. 1 Forward Current Derating Curve

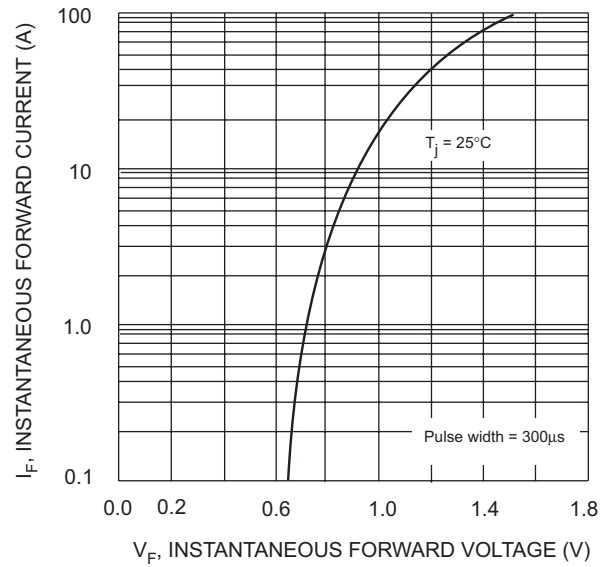


Fig. 2 Typical Fwd Characteristics, per element

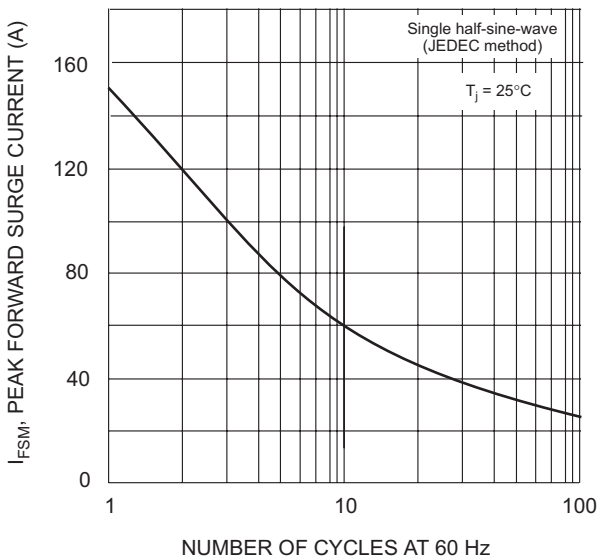


Fig. 3 Maximum Non-Repetitive Surge Current

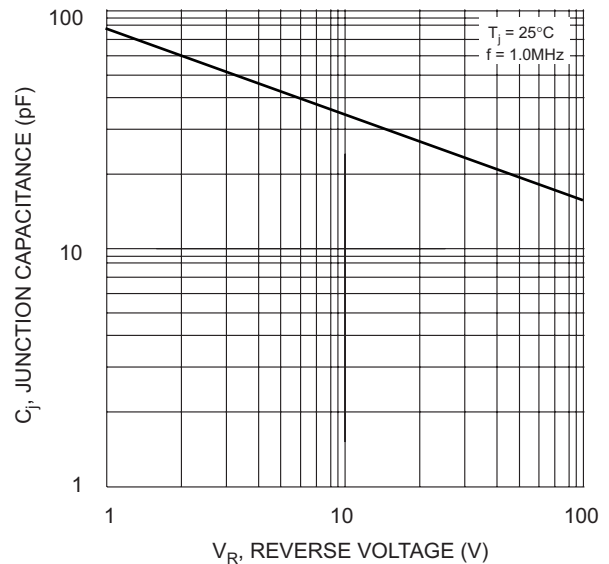


Fig. 4 Typical Junction Capacitance

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